

Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-586002	Application No.
Information Disclosure Statement by Applicant (Use several sheets if necessary). (37 CFR §1.98(b))		Applicant	
		Filing Date March 16, 2004	Group Art Unit

U.S. Patent Documents							
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
<i>SW</i>	AA	4,848,141	07/1989	Oliver et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						

Foreign Patent Documents or Published Foreign Patent Applications								
Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
	AH							
	AI							
	AJ							

Other Documents (include Author, Title, Date, and Place of Publication)		
Examiner Initial	Desig. ID	Document
<i>SW</i>	AK	P.T. Liu et al., Thin Solid Films 332 (1998) 345-350.
<i>SW</i>	AL	E. Kondoh, Electrochemical and Solid-State Letters, 1, (5) 224-226 (1998).
<i>SW</i>	AM	Gidley et. al., Applied Physics Letters, 76 (2000) p. 1282
<i>SW</i>	AN	Loboda et. al., Using trimethylsilane to improve safety, throughput and versatility in PECVD processes, Proceedings of the Symposium on Silicon Nitride and Silicon Dioxide Thin Insulating Films, 1997, p. 445-453.
<i>SW</i>	AO	Loboda et. al., Deposition of low-k dielectric films using trimethylsilane, Proceedings of the Symposia on Electrochemical Processing in ULSI Fabrication and Interconnect and Contact Metallization: Materials, Processes, and Reliability, 1998, p. 145-152.
<i>SW</i>	AP	Sugahara et. al., Low Dielectric Constant Carbon Containing SiO ₂ Films Deposited by PECVD Techniques Using a Novel CVD Precursor, International dielectrics for ULSI multilevel interconnection conference, 1997, p. 19-25.
<i>SW</i>	AQ	Kanaya K. and Okayama S., Journal of Physics D. Applied Physics. 5:43 (1972).
	AR	

Examiner Signature	Date Considered
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	